



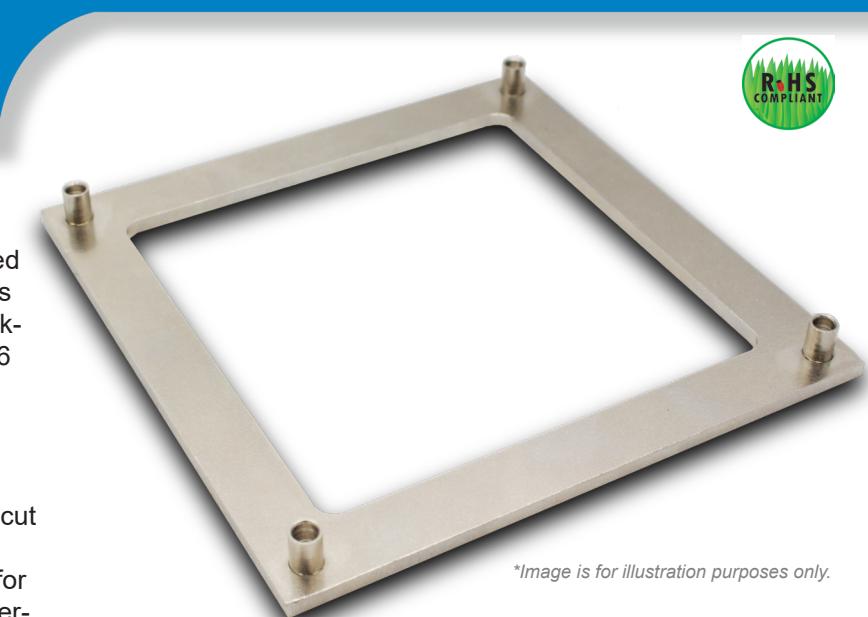
ATS-HK379-R0

The ATS-HK379-R0 is an optional backing plate designed for connecting CPUs and other high-powered processors (including GPUs, AI processors, and FPGAs) that fit sockets other than the Intel™ LGA2011 square and LGA2066 (Socket R) to the Ultra-Cool family of high-performance passive and active thermal solutions, including dual-FLOW™ and quadFLOW™.

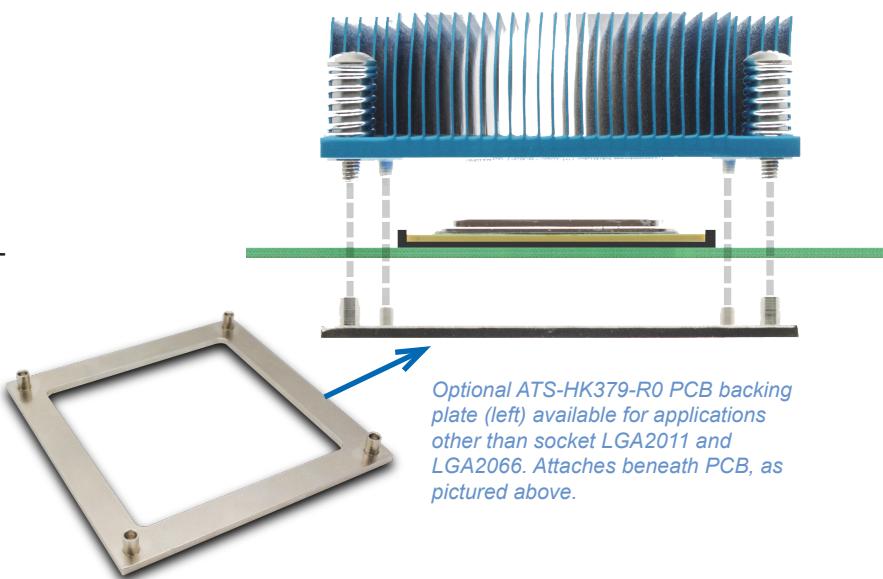
The ATS-HK379-R0 also comes with an unattached die-cut Formex GK-10 insulator to provide electrical insulation between the board and the backing plate. It is intended for use with 1.57-mm thick PCB. For applications with a different thickness PCB, contact ATS.

Features & Benefits

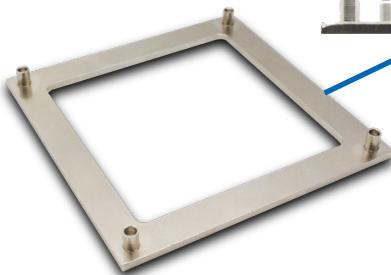
- « Dimensions (L x W): 96 x 96 mm (Inner Dimension: 70 x 70 mm)
- « Material: Steel (comes with unattached Formex GK-10 insulator)
- « Required mounting holes in PCB: 7.60 +0.35/-0.00 mm
- « Attaches beneath the PCB for even pressure across the board to prevent cracking or other damage
- « Backing Plate designed for use with 1.57-mm thick PCB
- « Mechanical attachment is PEM, screws and spring; For other types of attachments contact ATS
- « Final mounting pressure dependent on component height and contact area, contact ATS for details



*Image is for illustration purposes only.



Optional ATS-HK379-R0 PCB backing plate (left) available for applications other than socket LGA2011 and LGA2066. Attaches beneath PCB, as pictured above.



Product Details

Part Number	Material	Length (mm)	Width (mm)	Hole to Hole (mm)	Standoff Height (mm)	Inner Length (mm)	Inner Width (mm)
ATS-HK379-R0	Al	96	96	80	6.0	70	70

NOTES:

1. Backing Plate designed for use when LGA2011 and LGA2066 Socket not present
2. Backing Plate designed for use with 1.57-mm thick PCB
3. RoHS-6 and REACH compliant
4. For more information, contact ATS at ats-hq@qats.com



ATS-HK379-R0 (right) comes with Formex GK-10 insulator (left).

